FEDR48V256C-04
Issue Date: Nov. 15, 2018

MR48V256C

32,768-Word × 8-Bit FeRAM (Ferroelectric Random Access Memory)

GENERAL DESCRIPTION

The MR48V256C is a nonvolatile 32,768-word x 8-bit ferroelectric random access memory (FeRAM) developed in the ferroelectric process and silicon-gate CMOS technology. Unlike SRAMs, this device, whose cells are nonvolatile, eliminates battery backup required to hold data. This device has no mechanisms of erasing and programming memory cells and blocks, such as those used for various EEPROMs. Therefore, the write cycle time can be equal to the read cycle time and the power consumption during a write can be reduced significantly. The MR48V256C can be used in various applications, because the device is guaranteed for the write/read tolerance of 10^{13} cycles per bit and the rewrite count can be extended significantly.

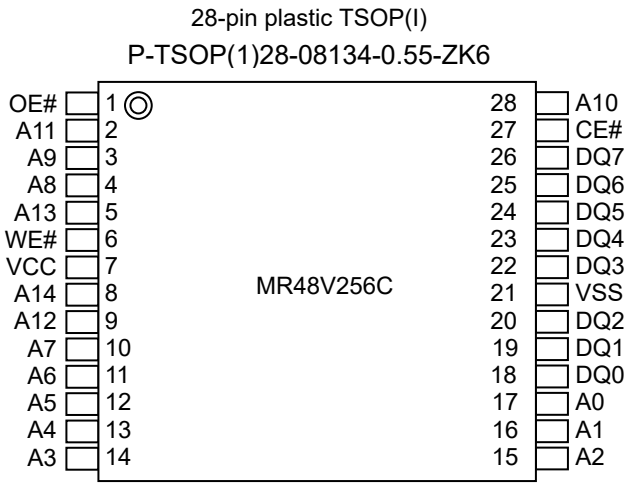
FEATURES

- 32,768-word × 8-bit configuration
- A single 2.7 to 3.6V power supply
- Read access time: 70 ns (Max.)
- Write enable time: 70 ns (Min.)
- Random read/write cycle time 150 ns (Min.)
- Read/write tolerance 10^{13} cycles/bit
- Data retention 10 years
- Guaranteed operating temperature range –40 to 85°C
- Package options:
  28-pin plastic TSOP(I) (TSOP(1)28-08134-0.55-ZK6)

PRODUCT FAMILY

Family	Access Time		Read/Write Cycle Time	Package
	Relative to CE	Relative to OE		
MR48V256C	70ns	40ns	150ns	28pin TSOP(I)

PIN CONFIGURATION



Note:
Signal names that end with # indicate that the pins are negative-true logic.

PIN DESCRIPTIONS

Pin Name	Description
CE#	Chip enable (input, negative logic) Latches an address by low input, activates the FeRAM, and enables a read or write operation.
OE#	Output enable (input, negative logic) The FeRAM is in read mode when the FeRAM is active and this pin is low, and data is output after the specified time.
WE#	Write enable (input, negative logic) The FeRAM is in write mode when the FeRAM is active and this pin is low, and data is capture at the timing of WE#="H" or CE#="H", whichever is earlier.
A14 to A0	Address (input) The FeRAM captures an address at the timing when CE#="L" is established.
DQ7 to DQ0	3-state data bus (input/output) Outputs data in the read mode, and captures data in the write mode.
V_{CC}, V_{SS}	Power supply Apply the specified voltage to V_{CC}. Connect V_{SS} to ground.

TRUTH TABLE

Operating Mode	CE#	WE#	OE#
Standby Mode	H	X	X
	X	H	H
Address Latched	↓	H	L
	↓	L	H
	L	↓	H
	L	H	↓
Read Mode	L	H	L
Write Mode	L	L	H

Note:
Having WE# and OE# “L” at the same time is forbidden.

ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Note
		Min.	Max.		
Pin Voltage (Input Signal)	V_{IN}	–0.5	V_{CC} + 0.5	V	
Pin Voltage (Input/Output Voltage)	V_{INQ}, V_{OUTQ}	–0.5	V_{CC} + 0.5	V	
Power Supply Voltage	V_{CC}	–0.5	4.6	V	
Storage Temperature (Extended Temperature Version)	Tstg	–55	125	°C	
Operating Temperature (Extended Temperature Version)	Topr	–40	85	°C	
Power Dissipation	P_D	1,000		mW	
Allowable Input Current	I_{IN}	±20		mA	Ta＝25°C
Allowable Output Current	I_{OUT}	±20		mA	Ta＝25°C

Note:
The application of stress (voltage, current, or temperature) that exceeds the absolute maximum rating may damage the device. Therefore, do not allow actual characteristics to exceed any one parameter ratings

Recommended Operating Conditions (Vss=0V)

Parameter	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	V_{CC}	2.7	3.6	V	3.3V typ.
Input High Voltage	V_{IH}	V_{CC} x 0.8	V_{CC} + 0.3	V	1
Input Low Voltage	V_{IL}	–0.3	V_{CC} x 0.15	V	2
Operating Temperature (Extended Temperature Version)	Ta	–40	85	°C	

Notes:
1. Overshoots with the pulse width of 20 ns or less and the voltage of V_{CC} + 1.0 V or less are allowed.
2. Undershoots with the pulse width of 20 ns or less and the voltage of −1.0 V or more are allowed.
3. The voltages are referenced to VSS

Capacitance

Parameter	Symbol	Min.	Max.	Unit	Note
Input Capacitance	C_{IN}	—	6	pF	1
Input/Output Capacitance	C_{OUT}	—	8	pF	1

Note:
Sampling value. Measurement conditions are V_{IN} = V_{OUT} = GND, f = 1MHz, and Ta = 25°C

DC Characteristics

(Under recommended operating conditions)

Parameter	Symbol	Condition	Min.	Max.	Unit	Note
Output High Voltage	V_{OH}	I_{OH} = –2 mA	$V_{CC} \times 0.85$	—	V	
Output Low Voltage	V_{OL}	I_{OL} = 2 mA	—	$V_{CC} \times 0.15$	V	
Input Leakage Current	I_{LI}	—	–10	10	µA	
Output Leakage Current	I_{LO}	—	–10	10	µA	
Power Supply Current (Standby)	I_{CCS}	V_{IN} = 0.2V or V_{CC}–0.2V, CE# = V_{CC}–0.2V I_{OUT} = 0 mA	—	400	µA	
Power Supply Current (Operating)	I_{CCA}	Read Cycle, t_{RC} = Min. V_{IN} = 0.2V or V_{CC}–0.2V, CE# = 0.2V, I_{OUT} = 0 mA	—	10	mA	1

Note:
1. Average current. Address change must be one time or less during time t_{RC}.

Read/Write Cycles and Data Retention

(Under recommended operating conditions)

Parameter	Min.	Max.	Unit	Note
Read/Write Cycle	10^{13}	—	Cycle	1, 2
Data Retention	10	—	Year	

Notes:
1. This is applicable to the read cycle, write cycle, and CE-only cycle counts. This is the cycle count per bit (for one address).
2. Total power on time ≤ 10 years

AC Characteristics (Read Cycle)

(Under recommended operating conditions)

Parameter	Symbol	Min.	Max.	Unit	Note
Address Set-up Time	t_{AVEL}	0	—	ns	
Address Hold Time (CE#)	t_{ELAX}	10	—	ns	
CE# High Pulse Width	t_{EHEL}	80	—	ns	
Output Hold Time (CE#)	t_{EHQX}	5	—	ns	
Output High Impedance Time (CE#)	t_{EHQZ}	—	25	ns	
CE# Active Time	t_{ELEH}	70	2000	ns	
Read Cycle Time (CE# cycle Time)	t_{ELEL}	150	—	ns	
CE# Access Time	t_{ELQV}	—	70	ns	1
Output Low Impedance Time (CE#)	t_{EHQX}	5	—	ns	
Output Hold Time (OE#)	t_{GHQX}	5	—	ns	
Output High Impedance Time (OE#)	t_{GHQZ}	—	25	ns	
OE# Access Time	t_{GLQV}	—	70	ns	1
Output Low Impedance Time (OE#)	t_{GLQX}	5	—	ns	

Notes:

1. The read data is output at the point where all of the maximum values of t_{ELQV} and t_{GLQV} are satisfied.

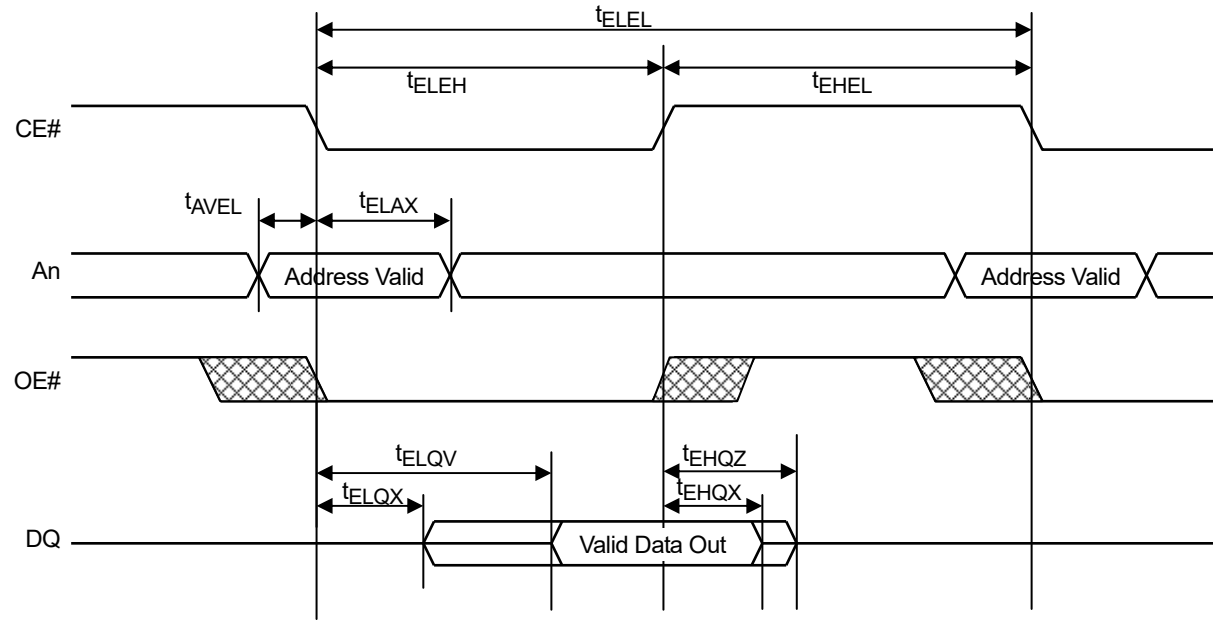
AC Characteristics (Write Cycle)

(Under recommended operating conditions)

Parameter	Symbol	Min.	Max.	Unit	Note
Address Set-up Time	t_{AVEL}	0	—	ns	
Address Hold Time	t_{ELAX}	10	—	ns	
Data Set-up Time (WE#)	t_{DVWH}	40	—	ns	
Data Hold Time (WE#)	t_{WHDX}	0	—	ns	
Data Set-up Time (CE#)	t_{DVEH}	40	—	ns	
Data Hold Time (CE#)	t_{EHDX}	0	—	ns	
CE# High Pulse Width	t_{EHEL}	80	—	ns	
CE# Active Time	t_{ELEH}	70	2000	ns	
Write Cycle Time (CE# Cycle Time)	t_{ELEL}	150	—	ns	

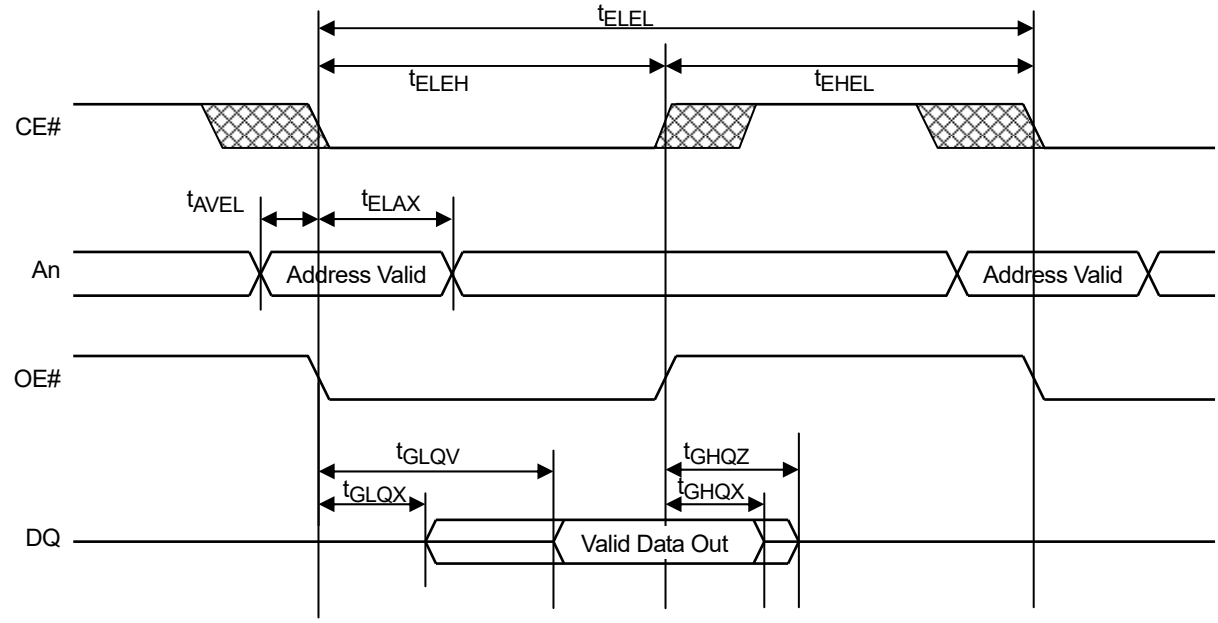
Timing Diagrams

•Read cycle, CE# Control Read



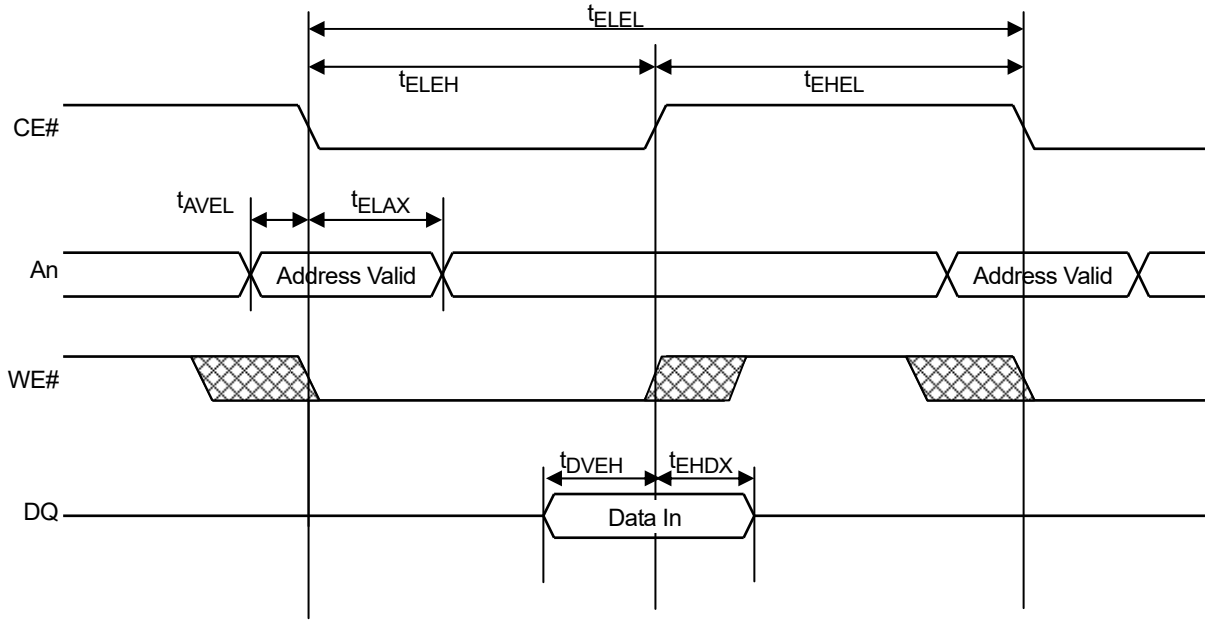
Note: WE# = "H"

•Read cycle, OE# Control Read



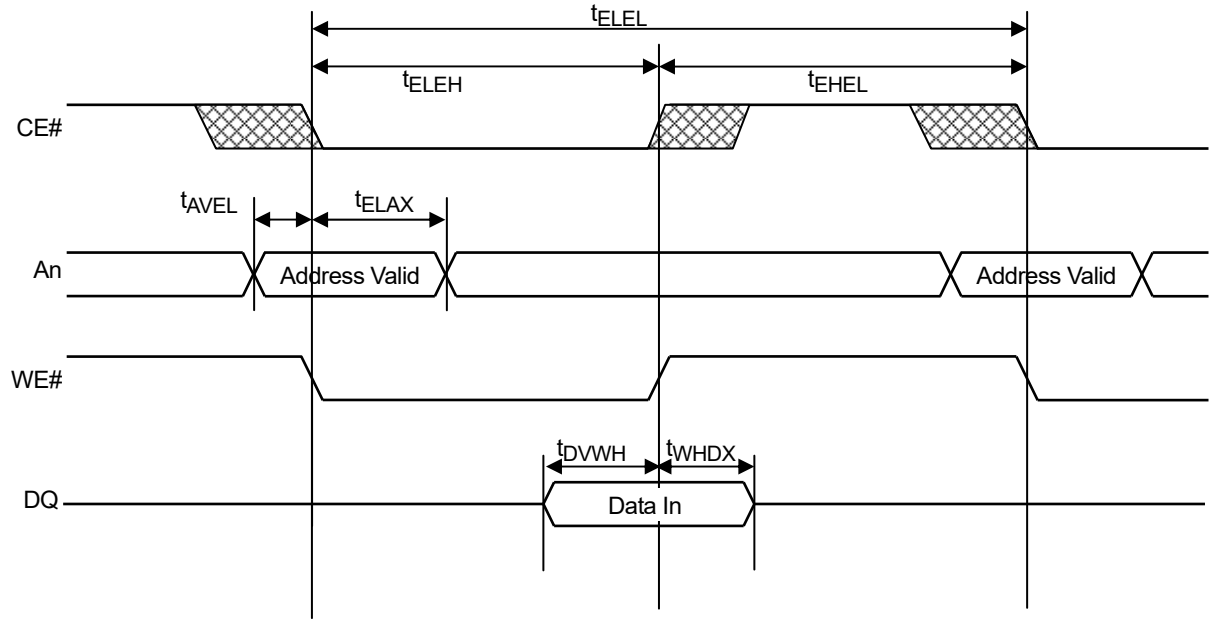
Note: WE# = "H"

•Write cycle, CE# Control Write



Note: OE# = “H”

•Write cycle, WE# Control Write



注記: OE#=”H”

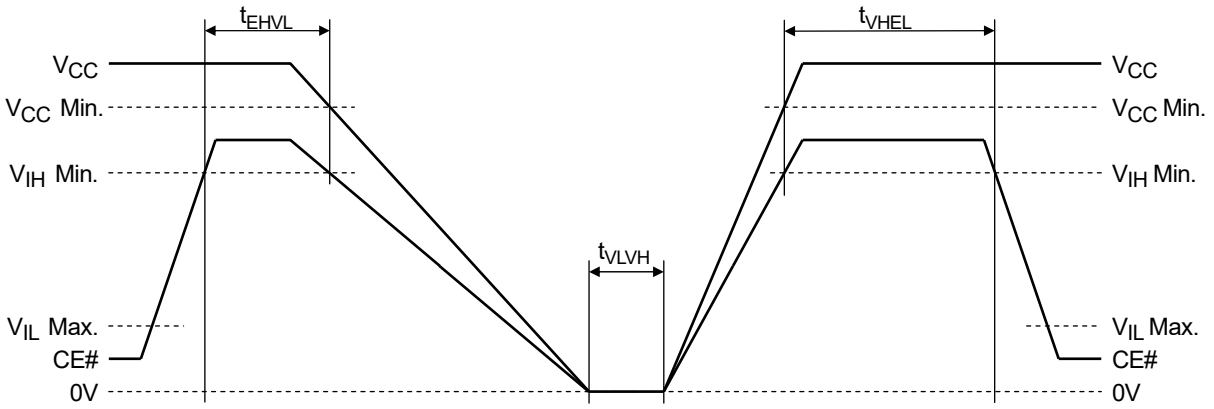
•Power-On and Power-Off Characteristics

(Under recommended operating conditions)

Parameter	Symbol	Min.	Max.	Unit	Note
Power-On CE# High Hold Time	t_{VHEL}	50	—	μs	1, 2
Power-Off CE# High Hold Time	t_{EHVL}	100	—	ns	1
Power-On Interval Time	t_{VLVH}	1	—	μs	2

Notes:
1. To prevent an erroneous operation, be sure to maintain CE#="H", and set the FeRAM in an inactive state (standby mode) before and after power-on and power-off.
2. Powering on at the intermediate voltage level will cause an erroneous operation; thus, be sure to power up from 0 V.
3. Enter all signals at the same time as power-on or enter all signals after power-on.

•Power-On and Power-Off Sequences



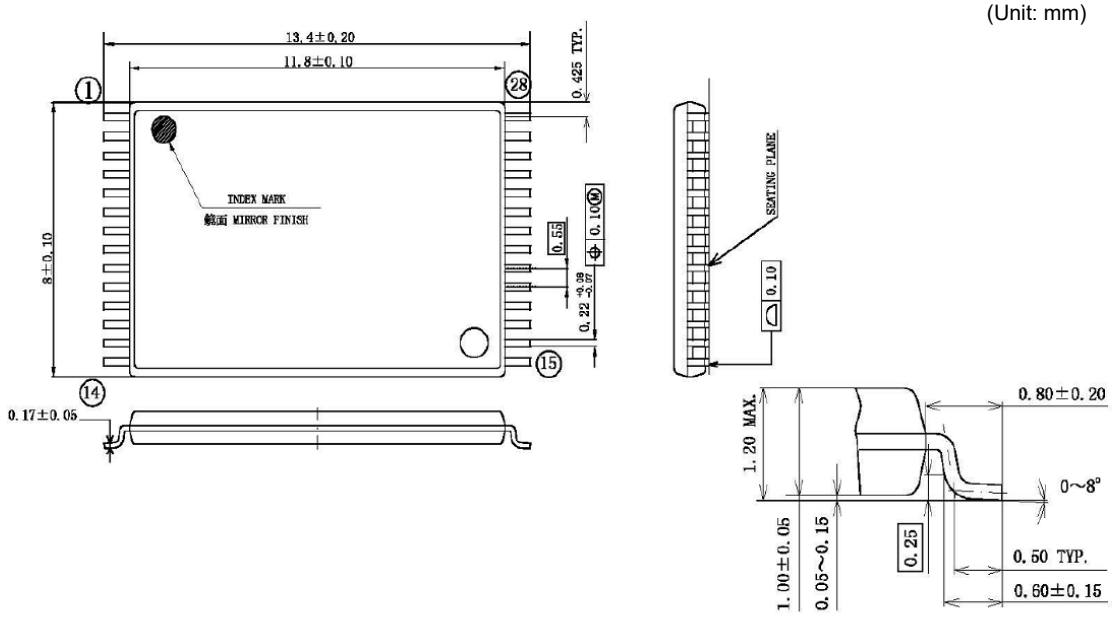
ORDERING INFORMATION

Product No.	Package Type (Package Code)	Packing	Temp. Range
MR48V256CTAZAAX	28-pin plastic TSOP(I) (TSOP(1)28-08134-0.55-ZK6)	Tray	−40 to 85°C

PACKAGE DIMENSIONS

P-TSOP(1)28-08134-0.55-ZK6

(Unit: mm)



NOTES:
1. LEAD WIDTH DOES NOT INCLUDE TRIM OFFSET.
2. PACKAGE WIDTH AND LENGTH DO NOT INCLUDE MOLD PROTRUSION DIEPAD SUPPORT PROTRUSION AND CAVITY OFFSET BETWEEN TOP AND BOTTOM CAVITY.
3. THE SEATING PLANE IS THE SURFACE WHICH THE PACKAGE IS MOUNTED ON AND GETS IN CONTACT WITH.

LAPIS Semiconductor Co.,Ltd.

Package material	Epoxy resin
Lead frame material	Cu alloy
Lead finish	Sn
Solder thickness	MORE THAN 5μm
Package weight (g)	0.237 TYP.
Rev. No./Last Revised	2 / Nov. 4, 2012

Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact a ROHM sales office for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

REVISION HISTORY

Document No.	Date	Page		Description
		Previous Edition	Current Edition	
FEDR48V256C-01	Nov. 13, 2013	–	–	Final Edition 1
FEDR48V256C-02	May 26, 2015	1 13	1 13	Changed New company logo. Changed Notes
FEDR48V256C-03	Jan. 19, 2017	7	7	Sorted an item.
FEDR48V256C-04	Nov. 15, 2018	1, 5 5 –	1, 5 5 11	Changed Read/write tolerance : 10^{12} cycles →10^{13} cycles Added Note2 Added ordering information

Notes

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